SCAS782B - SEPTEMBER 2004 - REVISED JANUARY 2008

	30A3702D - 3E1 TEMBER 2004 - RE	- • •
 Qualified for Automotive Applications Operates From 1.65 V to 3.6 V 	D OR PW PACKAGE (TOP VIEW)	
 Inputs Accept Voltages to 5.5 V 		
 Max t_{pd} of 6.2 ns 	1A 🛛 2 15 🗍 2🔂	
 Typical V_{OLP} (Output Ground Bounce) <0.8 V at V_{CC} = 3.3 V, T_A = 25°C 	1B [] 3 14 [] 2A 1Y0 [] 4 13 [] 2B	
 Typical V_{OHV} (Output V_{OH} Undershoot) >2 V at V_{CC} = 3.3 V, T_A = 25°C 	1Y1 [[5 12]] 2Y0 1Y2 []6 11 [] 2Y1	
 Latch-Up Performance Exceeds 250 mA Per JESD 17 	1Y3 7 10 2Y2 GND 8 9 2Y3	
ESD Protection Level Per AEC-Q100		

- ESD Protection Level Per AEC-Q100 Classification
 - 2000-V (H2) Human-Body Model
 - 200-V (M3) Machine Model
 - 1000-V (C5) Charged-Device Model

description/ordering information

This dual 2-line to 4-line decoder/demultiplexer is designed for 1.65-V to 3.6-V V_{CC} operation.

The device comprises two individual 2-line to 4-line decoders in a single package. The active-low enable (\overline{G}) input can be used as a data line in demultiplexing applications. This decoder/demultiplexer features fully buffered inputs, each of which represents only one normalized load to its driving circuit.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

ORDERING INFORMATION[†]

TA	PACKAGE [‡]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
40°C to 125°C	SOIC – D	Reel of 2500	SN74LVC139AQDRQ1	LVC139AQ
–40°C to 125°C	TSSOP – PW	Reel of 2000	SN74LVC139AQPWRQ1	LC139AQ

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

‡Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

FUNCTION TABLE (each decoder/demultiplexer)							
	INPUTS						
G	SEL	SELECT		OUTPUTS			
G	В	Α	Y3	Y2	Y1	Y0	
L	L	L	Н	Н	Н	L	
L	L	Н	н	Н	L	н	
L	Н	L	Н	L	Н	Н	
L	Н	Н	L	Н	Н	Н	
Н	Х	Х	Н	Н	Н	Н	



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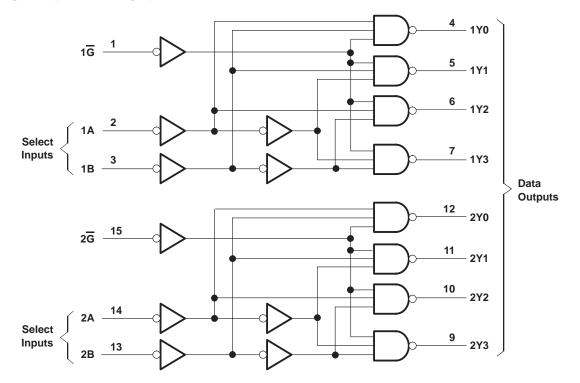
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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	–0.5 V to 6.5 V
Input voltage range, V _I (see Note 1)	–0.5 V to 6.5 V
Output voltage range, V _O (see Notes 1 and 2)	\dots –0.5 V to V _{CC} + 0.5 V
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I _{OK} (V _O < 0)	
Continuous output current, IO	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ_{JA} (see Note 3): D package	73°C/W
(see Note 3): PW package	108°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The value of V_{CC} is provided in the recommended operating conditions table.

3. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
		Operating	1.65	3.6		
VCC	Supply voltage	Data retention only	1.5		V	
		V _{CC} = 1.65 V to 1.95 V	$0.65 \times V_{CC}$			
VIH	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V	
		V _{CC} = 2.7 V to 3.6 V	2			
		V _{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$		
VIL	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
		V _{CC} = 2.7 V to 3.6 V		0.8		
VI	Input voltage		0	5.5	V	
VO	Output voltage		0	V _{CC}	V	
		V _{CC} = 1.65 V		-4		
1		V _{CC} = 2.3 V		-8	mA	
ЮН	High-level output current	$V_{CC} = 2.7 V$		-12		
		V _{CC} = 3 V		-24		
		V _{CC} = 1.65 V		4		
1		V _{CC} = 2.3 V		8	mA	
IOL	Low-level output current	V _{CC} = 2.7 V		12		
		V _{CC} = 3 V		24		
$\Delta t / \Delta v$	Input transition rise or fall rate			10	ns/V	
Τ _Α	Operating free-air temperature		-40	125	°C	

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	METED	TEAT CONDITIONS		T _A = -40	°C TO 12	25°C	$T_A = -40^{\circ}C \text{ TO } 85^{\circ}C$			
PARAMETER		TEST CONDITIONS	VCC	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT
		I _{OH} = -100 μA	1.65 V to 3.6 V	V _{CC} -0.2			V _{CC} – 0.2			
		$I_{OH} = -4 \text{ mA}$	1.65 V	1.2			1.2			
		I _{OH} = -8 mA	2.3 V	1.7			1.7			.,
Vон			2.7 V	2.1			2.2			V
		I _{OH} = –12 mA	3 V	2.3			2.4			
		I _{OH} = -24 mA	3 V	2.1			2.2			
		I _{OL} = 100 μA	1.65 V to 3.6 V			0.2			0.2	
		I _{OL} = 4 mA	1.65 V			0.45			0.45	
VOL		I _{OL} = 8 mA	2.3 V			0.7			0.7	V
		I _{OL} = 12 mA	2.7 V			0.4			0.4	
		I _{OL} = 24 mA	3 V			0.55			0.55	
Ц	All inputs	V _I = 5.5 V or GND	3.6 V			±5			±5	μΑ
ICC		$V_{I} = V_{CC} \text{ or GND}, I_{O} = 0$	3.6 V			10			10	μΑ
∆ICC		One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND	2.7 V to 3.6 V			500			500	μΑ
Ci		$V_I = V_{CC}$ or GND	3.3 V		5			5		pF

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25° C.

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switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

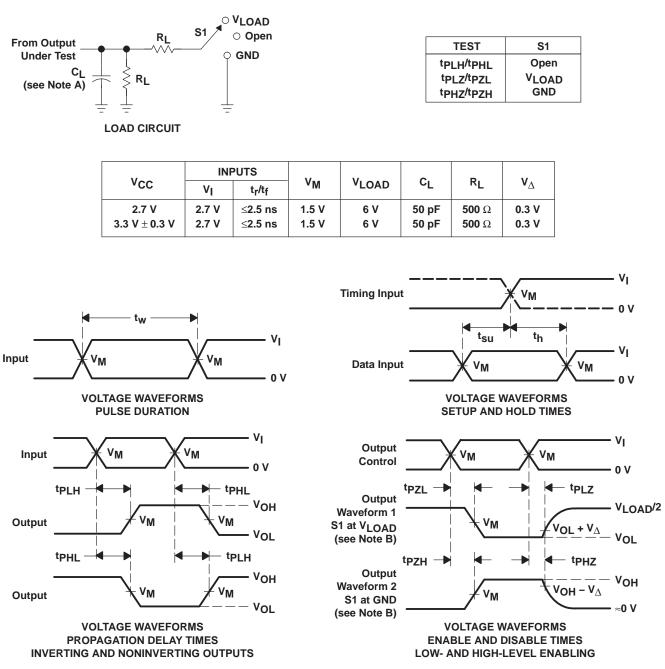
PARAMETER	FROM	TO	V _{CC} =	2.7 V	۲ <mark>0.3 V_{CC} =</mark>	3.3 V 3 V	UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	
	A or B	X	1	8.8	1	7.7	
^t pd	G	Ŷ	1	6.7	1	6.2	ns
^t sk(o)						1	ns

operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		TEST	V _{CC} = 1.8 V	V _{CC} = 2.5 V	V _{CC} = 3.3 V	UNIT
		CONDITIONS	TYP	TYP	TYP	UNIT
Cpd	Power dissipation capacitance	f = 10 MHz	28.5	29.5	30.5	pF



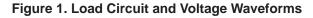
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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.





PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LVC139AQPWRQ1	ACTIVE	TSSOP	PW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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MECHANICAL DATA

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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